## **ABSOLUTE MAXIMUM RATINGS\***

ltem	Symbol	Rating	Units	
Voltage on Any Pin Relative to Vss	V <sub>IN</sub> , V <sub>OUT</sub>	-1 to +7.0	V	
Voltage on V <sub>CC</sub> Supply Relative to V <sub>ss</sub>	V <sub>cc</sub>	-1 to +7.0	٧	
Storage Temperature	T <sub>stg</sub>	- 55 to + 150	°C	
Power Dissipation	PD	600	mW	
Short Circuit Output Current	l <sub>os</sub> 50		mA	

<sup>\*</sup>Note: Permanent device damage may occur of "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# RECOMMENDED OPERATING CONDITIONS (Voltage reference to Vss, TA = 0 to 70°C)

Item	Symbol	Min	Тур	Max	Unit
Supply Voltage	V <sub>cc</sub>	4.5	5.0	5.5	٧
Ground	V <sub>ss</sub>	0	0	0	٧
Input High Voltage	V <sub>IH</sub>	2.4	<del></del>	V <sub>∞</sub> + 1	٧
Input Low Voltage	V <sub>IL</sub>	- 1.0		0.8	٧

## DC AND OPERATING CHARACTERISTICS

(Recommended operating conditions unless otherwise noted)

Parameter		Symbol	Min	Max	Units
Operating Current* (RAS, CAS, Address Cycling @t <sub>RC</sub> =min.)	KM41C464-7 KM41C464-8 KM41C464-10	I <sub>CC1</sub>	_ _ _	65 55 45	mA mA mA
Standby Current (RAS = CAS = V <sub>IH</sub> )		I <sub>CC2</sub>	_	2	mA
$\overline{RAS}$ -Only Refresh Current* ( $\overline{CAS} = V_{1H}$ , $\overline{RAS}$ Cycling $@t_{RC} = min.$ )	KM41C464-7 KM41C464-8 KM41C464-10	Iccs		65 55 45	mA mA mA
Fast Page Mode Current* (RAS=V <sub>IL</sub> , ČAŠ, Address Cycling @tpc=min.)	KM41C464-7 KM41C464-8 KM41C464-10	I <sub>CC4</sub>	<u>-</u> -	40 35 30	mA mA mA
Standby Current (RAS = CAS = V <sub>CC</sub> - 0.2V)		I <sub>CC5</sub>	_	1	mA
CAS-Before-RAS Refresh Current* (RAS and CAS Cycling @t <sub>RC</sub> = min.)	KM41C464-7 KM41C464-8 KM41C464-10	I <sub>CC6</sub>	_ _ _	65 55 45	mA mA mA
Input Leakage Current (Any input $0V \le V_{IN} \le 6.5V$ , all other pins not under test = 0 volts.)		I <sub>IL</sub>	- 10	10	μΑ
Output Leakage Current (Data out is disabled, 0≤V <sub>OUT</sub> ≤5.5V)		lou	- 10	10	μΑ
Output High Voltage Level (I <sub>OH</sub> = -5mA)		V <sub>OH</sub>	2.4	_	V
Output Low Voltage Level (I <sub>OL</sub> = 4.2mA)		V <sub>OL</sub>	_	0.4	V

<sup>\*</sup> NOTE:  $I_{CC1}$ ,  $I_{CC3}$ ,  $I_{CC4}$  and  $I_{CC6}$  are dependent on output loading and cycle rates. Specified values are obtained with the output open.  $I_{CC}$  is specified as average current.



# **CAPACITANCE** (T<sub>A</sub> = 25°C)

Item	Symbol	Min	Max	Unit
Input Capacitance (A <sub>0</sub> -A <sub>7</sub> )	C <sub>IN1</sub>	_	6	pF
Input Capacitance (RAS, CAS, W, OE)	C <sub>IN2</sub>	_	7	pF
Output Capacitance (DQ <sub>1</sub> -DQ <sub>4</sub> )	C <sub>DQ</sub>	_	7	pF

# AC CHARACTERISTICS (0°C $\leq$ T<sub>A</sub> $\leq$ 70°C, V<sub>CC</sub>=5.0V ± 10%. See notes 1, 2)

Parameter	Symbol	KM41C464-7		KM41C464-8		KM41C464-10			
		Min	Max	Min	Max	Min	Max	Unit	Notes
Random read or write cycle time	t <sub>RC</sub>	130		150		180		ns	
Read-modify-write cycle time	t <sub>RWC</sub>	185		205		245		ns	
Access time from RAS	t <sub>RAC</sub>		70		80		100	ns	3,4,11
Access time from CAS	t <sub>CAC</sub>		20		20		25	ns	3,4,5
Access time from column address	t <sub>AA</sub>		35		40		50	ns	3,10
CAS to output in Low-Z	t <sub>CLZ</sub>	0		0		0		ns	3
Output buffer turn-off delay	t <sub>OFF</sub>	0	25	0	25	0	30	ns	7
Transition time (rise and fall)	t⊤	3	50	3	50	3	50	ns	2
RAS precharge time	t <sub>RP</sub>	50		60		70		ns	
RAS pulse width	tras	70	10,000	80	10,000	100	10,000	ns	
RAS hold time	t <sub>RSH</sub>	20		20		25		ns	
CAS hold time	t <sub>CSH</sub>	70		80		100		ns	
CAS pulse width	t <sub>CAS</sub>	20	10,000	20	10,000	25	10,000	ns	
RAS to CAS delay time	t <sub>RCD</sub>	20	50	25	60	25	75	ns	4
RAS to column address delay time	t <sub>RAD</sub>	15	35	20	40	20	50	ns	11
CAS to RAS precharge time	t <sub>CRP</sub>	5		5		5		ns	
Row address set-up time	t <sub>ASR</sub>	0		0		0		ns	
Row address hold time	t <sub>RAH</sub>	10		15		15		ns	
Column address set-up time	t <sub>ASC</sub>	0		0		0		ns	
Column address hold time	t <sub>CAH</sub>	15		20		20		ns	
Column address hold time referenced to RAS	t <sub>AR</sub>	55		65		75		ns	6



# STANDARD OPERATION (Continued)

Parameter		KM41C464-7		KM41C464-8		KM41C464-10			
	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Column address to RAS lead time	t <sub>RAL</sub>	35		40		50		ns	-
Read command set-up time	t <sub>RCS</sub>	0		0		0		ns	
Read command hold referenced to CAS	t <sub>RCH</sub>	0		0		0		ns	9
Read command hold referenced to RAS	t <sub>RRH</sub>	0		0		0		ns	9
Write command hold time	twch	15		15		20		ns	
Write command hold time referenced to RAS	twcn	55		60		75		ns	6
Write command pulse width	t <sub>WP</sub>	15		15		20		ns	
Write command to RAS lead time	t <sub>RWL</sub>	20		20		25		ns	
Write command to CAS lead time	t <sub>CWL</sub>	20		20		25		ns	
Data-in set-up time	t <sub>DS</sub>	0		0		0		ns	10
Data hold time	t <sub>DH</sub>	15		15		20		ns	10
Data hold referenced to RAS	tohr	55		60		75		ns	6
Refresh period (256 cycles)	t <sub>REF</sub>		4		4		4	ms	
Write command set-up time	twcs	0		0		0		ns	8
CAS to W delay time	t <sub>CWD</sub>	50		50		50		ns	8
RAS to W delay time	t <sub>RWD</sub>	100		110		135		ns	8
Column address to W delay time	t <sub>AWD</sub>	65		70		85		ns	8
CAS set-up time (CAS Before RAS refresh)	t <sub>CSR</sub>	10		10		10		ns	
CAS hold time (CAS Before RAS refresh)	t <sub>CHR</sub>	20		25		30		ns	
RAS precharge to CAS hold time	t <sub>RPC</sub>	10		10		10		ns	
Refresh counter test CAS precharge time	t <sub>CPT</sub>	35		40		50		ns	
Fast Page mode cycle time	t <sub>PC</sub>	45		50		60		ns	
CAS precharge time (Fast page mode)	t <sub>CP</sub>	10		10		10		ns	
Access time from CAS precharge	t <sub>CPA</sub>		45		45		55	ns	3
Fast page mode read-modify-write	t <sub>PRWC</sub>	100		105		125		ns	
RAS pulse width (Fast Page mode)	tRASP	70	100,000	80	100,000	100	100,000	ns	<u></u>
RAS hold time referenced to OE	t <sub>ROH</sub>	15		20		20		ns	
OE access time	t <sub>OEA</sub>		20		20		25	ns	
OE to data delay	t <sub>OED</sub>	20		20		25		ns	
Output buffer turn off delay OE	t <sub>OEZ</sub>	0	20	0	20	0	25	ns	
OE command hold time	t <sub>OEH</sub>	20		20		25		ns	

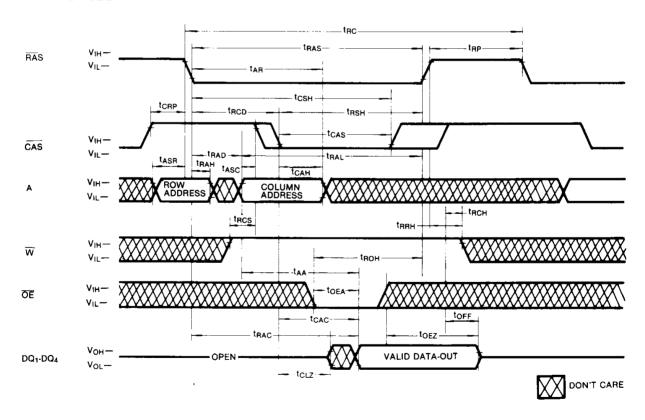
KM41C464 CMOS DRAM

#### **NOTES**

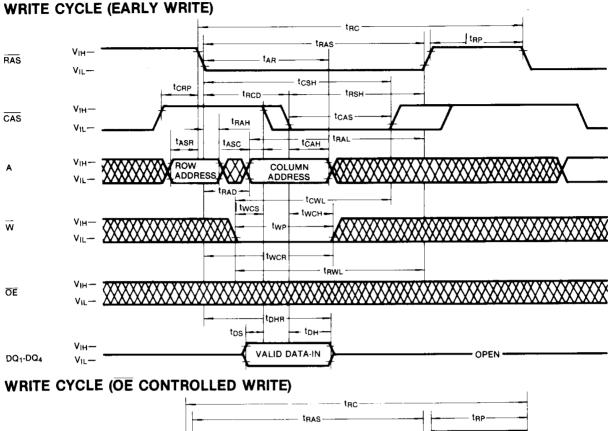
- 2.  $V_{IH}(min)$  and  $V_{IL}(max)$  are reference levels for measuring timing of input signals. Transition times are measured between  $V_{IH}(min)$  and  $V_{IL}(max)$  and are assumed to be 5ns for all inputs.
- 3. Measured with a load equivalent to 2 TTL loads and 100pF.
- 4. Operation within the t<sub>RCD</sub>(max) limit insures the t<sub>RAC</sub>(max) can be met. t<sub>RCD</sub>(max) is specified as a reference point only. If t<sub>RCD</sub> is greater than the specified t<sub>RCD</sub>(max) limit, then access time is controlled exclusively by t<sub>CAC</sub>.
- 5. Assumes that  $t_{RCD} \ge t_{RCD}(max)$ .
- 6. tAR, tWCR, tDHR are referenced to tRAD(max).
- 7. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to V<sub>OH</sub> or V<sub>OL</sub>.
- 8. t<sub>WCS</sub>, t<sub>RWD</sub>, t<sub>CWD</sub> and t<sub>AWD</sub> are non restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If t<sub>WCS</sub>≥t<sub>WCS</sub>(min) the cycle is an early write cycle and the data out pin will remain high impedance for the duration of the cycle. If t<sub>CWD</sub>≥t<sub>CWD</sub>(min) and t<sub>RWD</sub><t<sub>RWD</sub>(min) and <sub>AWD</sub>≥t<sub>AWD</sub>(min), then the cycle is a read-write cycle and the data out will contain the data read from the selected address. If neither of the above conditions are satisfied, the condition of the data out is indeterminate.
- 9. Either  $t_{\text{RCH}}$  or  $t_{\text{RRH}}$  must be satisfied for a read cycle.
- 10. These parameters are referenced to the  $\overline{\text{CAS}}$  leading edge in early write cycles and to the  $\overline{\text{W}}$  leading edge in read-write cycles.
- 11. Operation within the  $t_{RAD}(max)$  limit insures that  $t_{RAD}(max)$  can be met.  $t_{RAD}(max)$  is specified as a reference point only. If  $t_{RAD}$  is greater than the specified  $t_{RAD}(max)$  limit, then access time is controlled by  $t_{AA}$ .

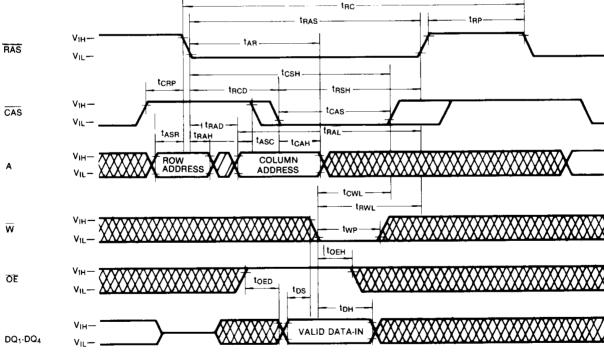
## **TIMING DIAGRAMS**

#### **READ CYCLE**







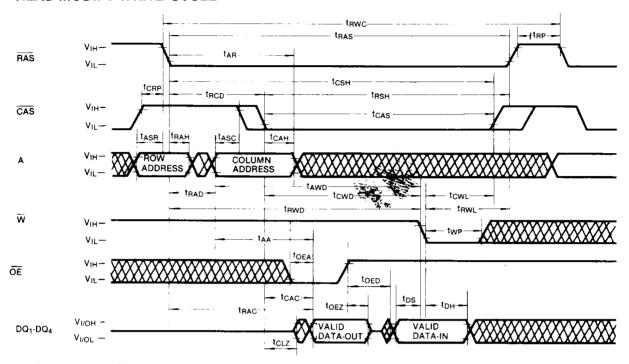




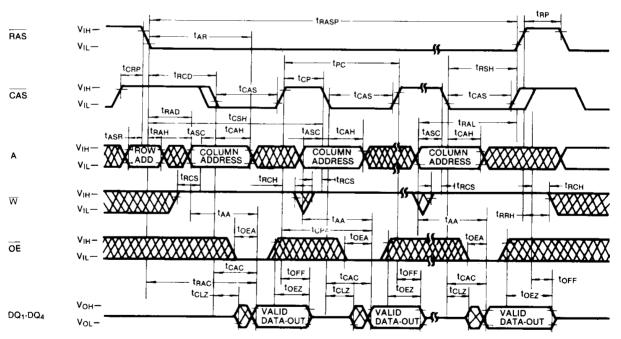
KM41C464 CMOS DRAM

## TIMING DIAGRAMS (Continued)

## **READ-MODIFY-WRITE CYCLE**

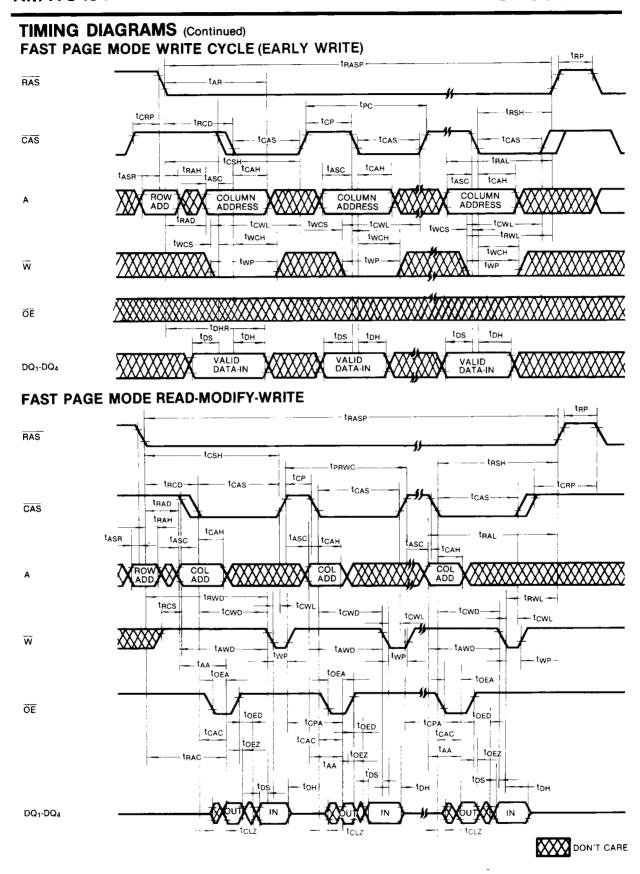


### **FAST PAGE MODE READ CYCLE**





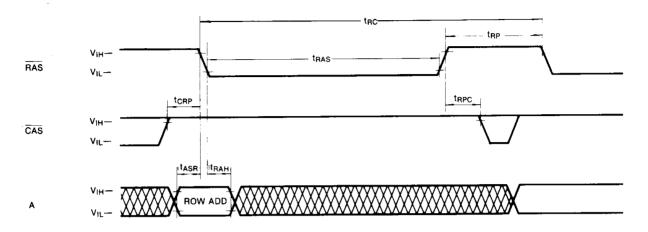






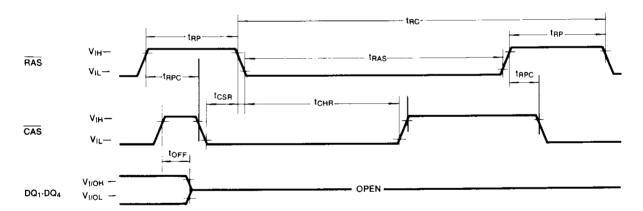
## **RAS-ONLY REFRESH CYCLE**

Note:  $\overline{W}$ ,  $\overline{OE}$  = Don't care



## CAS-BEFORE-RAS REFRESH CYCLE

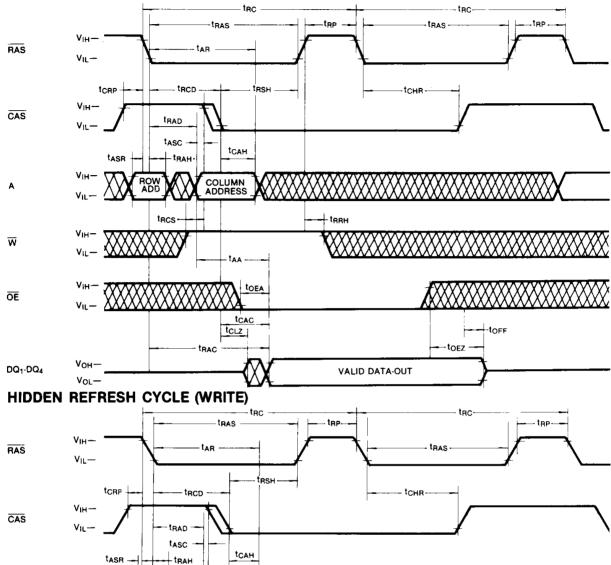
Note:  $\overline{W}$ ;  $\overline{OE}$ , A = Don't care

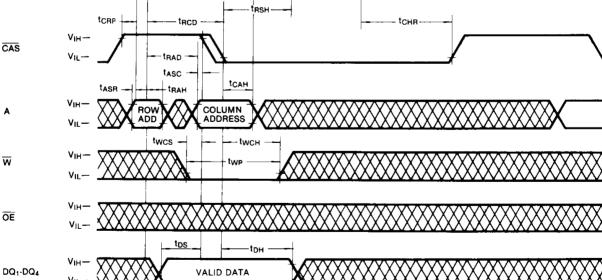






## **HIDDEN REFRESH CYCLE (READ)**



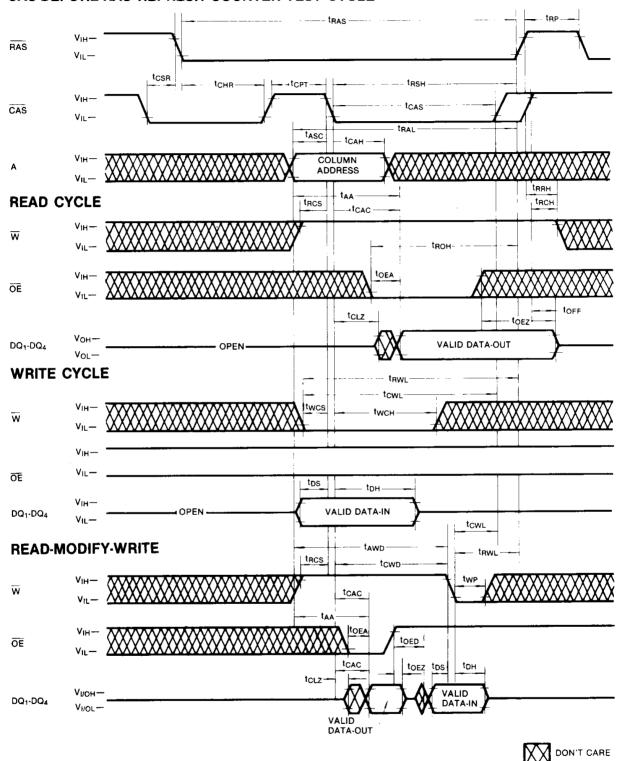


**t**DHR



XX DON'T CARE

## CAS-BEFORE-RAS REFRESH COUNTER TEST CYCLE





#### **DEVICE OPERATION**

### **Device Operation**

The KM41C464 contains 262,144 memory locations organized as 65,536 four-bit words. Sixteen address bits are required to address a particular 4-bit word in the memory array. Since the KM41C464 has only 8 address input pins, time multiplexed addressing is used to input 8 row and 8 column addresses. The multiplexing is controlled by the timing relationship between the row address strobe (RAS), the column address strobe (CAS) and the valid address inputs.

Operation of the KM41C464 begins by strobing in a valid row address with  $\overline{RAS}$  while  $\overline{CAS}$  remains high. Then the address on the 8 address input pins is changed from a row address to a column address and is strobed in by CAS. This is the beginning of any KM41C464 cycle in which a memory location is accessed. The specific type of cycle is determined by the state of the write enable pin and various timing relationships. The cycle is terminated when both  $\overline{RAS}$  and  $\overline{CAS}$  have returned to the high state. Another cycle can be initiated after RAS remains high long enough to satisfy the  $\overline{RAS}$  precharge time ( $t_{RP}$ ) requirement.

### RAS and CAS Timing

The minimum  $\overline{RAS}$  and  $\overline{CAS}$  pulse widths are specified by  $t_{RAS}(min)$  and  $t_{CAS}(min)$  respectively. These minimum pulse widths must be satisfied for proper device operation and data integrity. Once a cycle is initiated by bringing  $\overline{RAS}$  low, it must not be aborted prior to satisfying the minimum  $\overline{RAS}$  and  $\overline{CAS}$  pulse widths. In addition, a new cycle must not begin until the minimum  $\overline{RAS}$  precharge time,  $t_{RP}$ , has been satisfied. Once a cycle begins, internal clocks and other circuits within the KM41C464 begin a complex sequence of events. If the sequence is broken by violating minimum timing requirements, loss of data integrity can occur.

#### Read

A read cycle is achieved by maintaining the write enable input(W) high during a  $\overline{\text{RAS}}/\overline{\text{CAS}}$  cycle. The access time is normally specified with respect to the falling edge of  $\overline{\text{RAS}}$ . But the access time also depends on the falling edge of  $\overline{\text{CAS}}$  and on the valid column address transition. If  $\overline{\text{CAS}}$  goes low before  $t_{\text{RCD}}(\text{max})$  and if the column address is valid before  $t_{\text{RAD}}(\text{max})$  then the access time to valid data is specified by  $t_{\text{RAC}}(\text{min})$ . However, if  $\overline{\text{CAS}}$  goes low after  $t_{\text{RCD}}(\text{max})$  or if the column address becomes valid after  $t_{\text{RAD}}(\text{max})$ , access is specified by  $t_{\text{CAC}}$  or  $t_{\text{AA}}$ . In order to achieve the minimum access time,  $t_{\text{RAC}}(\text{min})$ , it is necessary to meet both  $t_{\text{RCD}}(\text{max})$  and  $t_{\text{RAD}}(\text{max})$ .

The KM41C464 has common data I/O pins. For this reason an output enable control input ( $\overline{OE}$ ) has been provided so the output buffer can be precisely controlled. For data to apppear at the outputs, OE must be low for the period of time defined by  $t_{OEA}$  and  $t_{OFZ}$ .

#### Write

The KM41C464 can perform early write and read-modify-write cycles. The difference between these cycles is in the state of data-out and is determined by the timing relationship between W, OE and CAS. In any type of write cycle Data-in must be valid at or before the falling edge of W or CAS, whichever is later.

Early Write: An early write cycle is performed by bringing  $\overline{W}$  low before  $\overline{CAS}$ . The 4-bit wide data at the data input pins is written into the addressed memory cells. Throughout the early write cycle the outputs remain in the Hi-Z state. In the early write cycle the output buffers remain in the Hi-Z state regardless of the state of the  $\overline{OE}$  input.

Read-Modify-Write: In this cycle, valid data from the addressed cells appears at the outputs before and during the time that data is being written into the same cell locations. This cycle is achieved by bringing W low after  $\overline{\text{CAS}}$  and meeting the data sheet read-modify-write timing requirements. The output enable input ( $\overline{\text{OE}}$ ) must be low during the time defined by  $t_{\text{OEA}}$  and  $t_{\text{OEZ}}$  for data to appear at the outputs. If  $t_{\text{CWD}}$  and  $t_{\text{RWD}}$  are not met the output may contain invalid data. Conforming to the  $\overline{\text{OE}}$  timing requirements prevents bus contention on the KM41C464's DQ pins.

### **Data Output**

The KM41C464 has a three-state output buffers which are controlled by  $\overline{CAS}$  and  $\overline{OE}$ . When either  $\overline{CAS}$  or  $\overline{OE}$  is high (V<sub>IH</sub>) the output are in the high impedance (Hi-Z) state. In any cycle in which valid data appears at the output the output goes into the low impedance state in a time specified by  $t_{CLZ}$  after the falling edge of  $\overline{CAS}$ . Invalid data may be present at the output during the time after  $t_{CLZ}$  and before the valid data appears at the output. The timing parameters  $t_{CAC}$ ,  $t_{RAC}$  and  $t_{AA}$  specify when the valid data will be present at the output. This is true even if a new  $\overline{RAS}$  cycle occurs (as in hidden refresh). Each of the KM41C464 operating cycles is listed below after the corresponding output state produced by the cycle.

Valid Output Data: Read, Read-Modify-Write, Hidden Refresh, Fast Page Mode Read, Fast Page Mode Read-Modify-Write.

Hi-Z Output State: Early Write, RAS-only Refresh, Fast Page Mode Write, CAS-only cycle.

Indeterminate Output State: Delayed Write ( $t_{\text{CWD}}$  or  $t_{\text{RWD}}$  are not met)

#### Refresh

The data in the KM41C464 is stored on a tiny capacitor within each memory cell. Due to leakage the data may leak off after a period of time. To maintain data integrity it is necessary to refresh each of the rows every 4 ms. Either a burst refresh or distributed refresh may be



KM41C464 CMOS DRAM

## **DEVICE OPERATION** (Continued)

used. There are several ways to accomplish this.

 $\overline{RAS}$ -Only Refresh: This is the most common method for performing refresh. It is performed by strobing in a row address with  $\overline{RAS}$  while  $\overline{CAS}$  remains high. This cycle must be repeated for each of the 256 row addresses,  $(A_0$ - $A_7)$ .

CAS-before-RAS Refresh: The KM41C464 has CAS-before-RAS on-chip refresh capability that eliminates the need for external refresh addresses. If CAS is held low for the specified set up time (t<sub>CSR</sub>) before RAS goes low, the on-chip refresh circuitry is enabled. An internal refresh operation automatically occurs. The refresh address is supplied by the on-chip refresh address counter which is then internally incremented in preparation for the next CAS-before-RAS refresh cycle.

Hidden Refresh: A hidden refresh cycle may be performed while maintaining the latest valid data at the output by extending the CAS active time and cycling RAS. The KM41C464 hidden refresh cycle is actually a CAS-before-RAS refresh cycle within an extended read cycle. The refresh row address is provided by the on-chip refresh address counter.

Other Refresh Methods: It is also possible to refresh the KM41C464 by using read, write or read-modify-write

cycles. Whenever a row is accessed, all the cells in that row are automatically refreshed. There are certain applications in which it might be advantageous to perform refresh in this manner but in general RAS-only or CAS-before-RAS refresh is the preferred method.

## Fast Page Mode

Fast page mode provides high speed read, write or read-modify-write access to all memory cells within a selected row. These cycles may be mixed in any order. A fast page mode cycle begins with a normal cycle. Then, while RAS is kept low to maintain the row address, CAS is cycled to strobe in additional column addresses. This eliminates the time required to set up and strobe sequential row addresses for the same page.

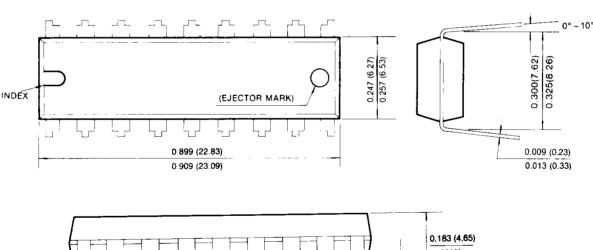
### CAS-Before-RAS Refresh Counter Test Cycle

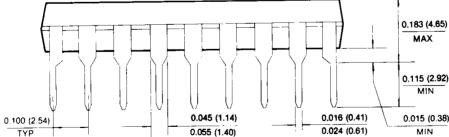
A special timing sequence using the  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  counter test cycle provides a convenient method of verifying the functionality of the  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  refresh activated circuitry. The cycle begins as a  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  refresh operation. Then, if  $\overline{\text{CAS}}$  is brought high and then low again while  $\overline{\text{RAS}}$  is held low, the read and write operations are enabled. In this mode, the row address bits  $A_0$  through  $A_7$  are supplied by the on-chip refresh counter.

## PACKAGE DIMENSIONS

### 18-LEAD PLASTIC DUAL IN-LINE PACKAGE

Units: Inches (millimeters)

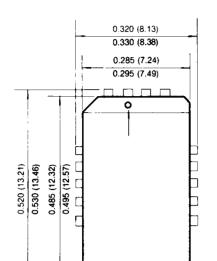


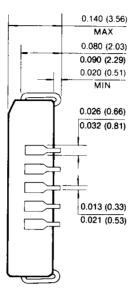


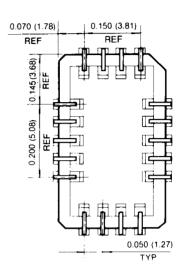


# PACKAGE DIMENSIONS (Continued)

## 18-PIN PLASTIC LEADED CHIP CARRIER

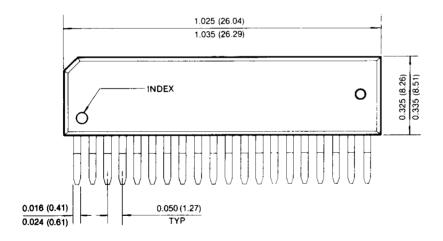


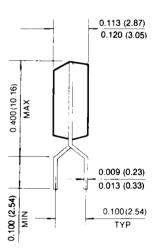




Units: Inches (Millimeters)

## 20-PIN PLASTIC ZIGZAG-IN-LINE PACKAGE





## **DEVICE OPERATION** (Continued)

used. There are several ways to accomplish this.

RAS-Only Refresh: This is the most common method for performing refresh. It is performed by strobing in a row address with RAS while CAS remains high. This cycle must be repeated for each of the 256 row addresses,

CAS-before-RAS Refresh: The KM41C464 has CASbefore-RAS on-chip refresh capability that eliminates the need for external refresh addresses. If CAS is held low for the specified set up time (t<sub>CSR</sub>) before RAS goes low, the on-chip refresh circuitry is enabled. An internal refresh operation automatically occurs. The refresh address is supplied by the on-chip refresh address counter which is then internally incremented in preparation for the next CAS-before-RAS refresh cycle.

Hidden Refresh: A hidden refresh cycle may be performed while maintaining the latest valid data at the output by extending the CAS active time and cycling RAS. The KM41C464 hidden refresh cycle is actually a CAS-before-RAS refresh cycle within an extended read cycle. The refresh row address is provided by the on-chip refresh address counter.

Other Refresh Methods: It is also possible to refresh the KM41C464 by using read, write or read-modify-write

cycles. Whenever a row is accessed, all the cells in that row are automatically refreshed. There are certain applications in which it might be advantageous to perform refresh in this manner but in general RAS-only or CASbefore-RAS refresh is the preferred method.

### **Fast Page Mode**

Fast page mode provides high speed read, write or readmodify-write access to all memory cells within a selected row. These cycles may be mixed in any order. A fast page mode cycle begins with a normal cycle. Then, while RAS is kept low to maintain the row address, CAS is cycled to strobe in additional column addresses. This eliminates the time required to set up and strobe sequential row addresses for the same page.

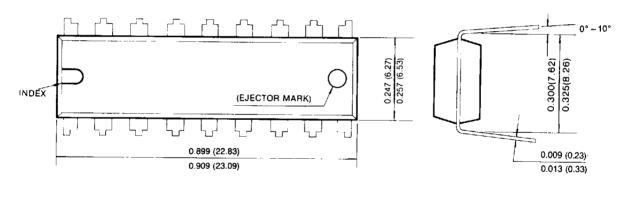
## **CAS-Before-RAS** Refresh Counter Test Cycle

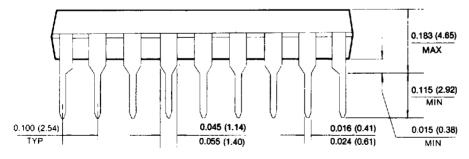
A special timing sequence using the CAS-before-RAS counter test cycle provides a convenient method of verifying the functionality of the CAS-before-RAS refresh activated circuitry. The cycle begins as a CAS-before-RAS refresh operation. Then, if CAS is brought high and then low again while RAS is held low, the read and write operations are enabled. In this mode, the row address bits Ao through A7 are supplied by the on-chip refresh counter.

## PACKAGE DIMENSIONS

18 LEAD PLASTIC DUAL IN LINE PACKAGE

Units: Inches (millimeters)







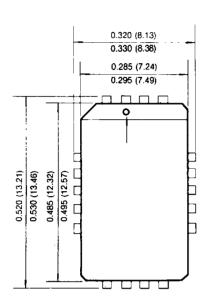
2

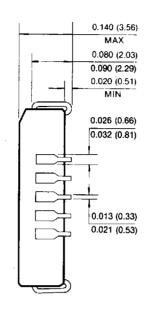
# **CMOS DRAM**

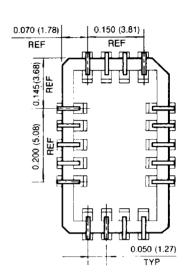
## PACKAGE DIMENSIONS (Continued)

### 18-PIN PLASTIC LEADED CHIP CARRIER

Units: Inches (Millimeters)







## 20-PIN PLASTIC ZIGZAG-IN-LINE PACKAGE

